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NLU3G16

Triple Non-Inverting Buffer

The NLU3G16 MiniGate™ is an advanced high−speed CMOS triple non−inverting buffer in ultra−small footprint.

The NLU3G16 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: t_{PD} = 3.5 ns (Typ) @ V_{CC} = 5.0 V
- Low Power Dissipation: I_{CC} = 1 μA (Max) at T_A = 25°C
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Overvoltage Tolerant (OVT) Input and Output Pins
- Ultra−Small Packages
- These are Pb−Free Devices

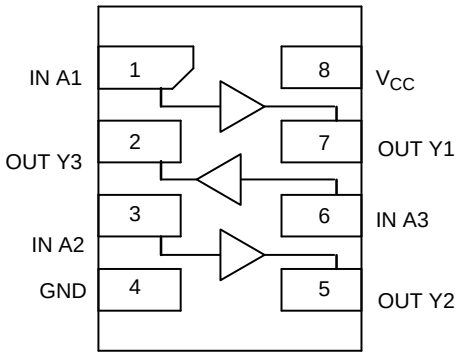

Figure 1. Pinout (Top View)

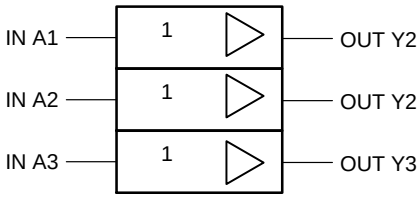

Figure 2. Logic Symbol

PIN ASSIGNMENT

1	IN A1
2	OUT Y3
3	IN A2
4	GND
5	OUT Y2
6	IN A3
7	OUT Y1
8	V_{CC}

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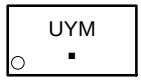
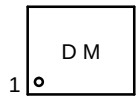
MARKING DIAGRAMS

UDFN8
1.8 x 1.2
CASE 517AJ



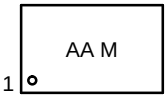
ULLGA8
1.95 x 1.0
CASE 613AC

UDFN8
1.45x1, 0.35P
CASE 517BZ



UDFN8
1.6x1, 0.4P
CASE 517BY

UDFN8
1.95x1, 0.5P
CASE 517CA



UY, R or LR = Specific Device Code
M = Date Code
▪ = Pb−Free Package

FUNCTION TABLE

A	Y
L	L
H	H

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage	−0.5 to +7.0	V
V_{IN}	DC Input Voltage	−0.5 to +7.0	V
V_{OUT}	DC Output Voltage	−0.5 to +7.0	V
I_{IK}	DC Input Diode Current V_{IN} < GND	−20	mA
I_{OK}	DC Output Diode Current V_{OUT} < GND	±20	mA
I_O	DC Output Source/Sink Current	±12.5	mA
I_{CC}	DC Supply Current Per Supply Pin	±25	mA
I_{GND}	DC Ground Current per Ground Pin	±25	mA
T_{STG}	Storage Temperature Range	−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T_J	Junction Temperature Under Bias	150	°C
MSL	Moisture Sensitivity	Level 1	
F_R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V−0 @ 0.125 in	
$I_{LATCHUP}$	Latchup Performance Above V_{CC} and Below GND at 125°C (Note 2)	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm−by−1 inch, 2 ounce copper trace no air flow.
2. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V_{CC}	Positive DC Supply Voltage		1.65	5.5	V
V_{IN}	Digital Input Voltage		0	5.5	V
V_{OUT}	Output Voltage		0	5.5	V
T_A	Operating Free−Air Temperature		−55	+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	V_{CC} = 3.3 V ± 0.3 V V_{CC} = 5.0 V ± 0.5 V	0 0	100 20	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V_{CC} (V)	T_A = 25 °C			T_A = +85°C		T_A = −55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
V_{IH}	Low−Level Input Voltage		1.65	0.75 x V_{CC}			0.75 x V_{CC}				V
			2.3 to 5.5	0.70 x V_{CC}			0.70 x V_{CC}				
V_{IL}	Low−Level Input Voltage		1.65			0.25 x V_{CC}		0.25 x V_{CC}		0.25 x V_{CC}	V
			2.3 to 5.5			0.30 x V_{CC}		0.30 x V_{CC}		0.30 x V_{CC}	
V_{OH}	High−Level Output Voltage	V_{IN} = V_{IH} or V_{IL} I_{OH} = −50 μA	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		V_{IN} = V_{IH} or V_{IL} I_{OH} = −4 mA I_{OH} = −8 mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		V
V_{OL}	Low−Level Output Voltage	V_{IN} = V_{IH} or V_{IL} I_{OL} = 50 μA	2.0 3.0 4.5		0 0 0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		V_{IN} = V_{IH} or V_{IL} I_{OL} = 4 mA I_{OL} = 8 mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I_{IN}	Input Leakage Current	0 ≤ V_{IN} ≤ 5.5 V	0 to 5.5			±0.1		±1.0		±1.0	μA
I_{CC}	Quiescent Supply Current	V_{IN} = V_{CC} or GND	5.5			1.0		10		40	μA

AC ELECTRICAL CHARACTERISTICS (Input t_r = t_f = 3.0 ns)

Symbol	Parameter	V_{CC} (V)	Test Condition	T_A = 25 °C			T_A = +85°C		T_A = −55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t_{PLH}, t_{PHL}	Propagation Delay, Input A to Output $\overline{Y}$	3.0 to 3.6	C_L = 15 pF		4.5	7.1		8.5		10	ns
			C_L = 50 pF		6.4	10.6		12		14.5	
		4.5 to 5.5	C_L = 15 pF		3.5	5.5		6.5		8.0	
			C_L = 50 pF		4.5	7.5		8.5		10	
C_{IN}	Input Capacitance				4.0	10		10		10	pF
C_{PD}	Power Dissipation Capacitance (Note 3)	5.0			8.0						pF

3. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no−load dynamic power consumption: $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

SWITCHING WAVEFORMS

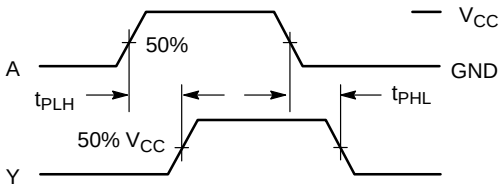
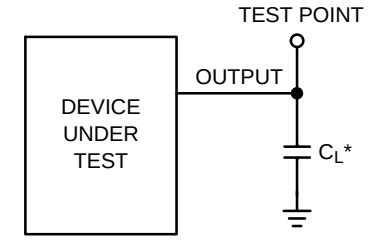


Figure 3. Switching Waveforms



*Includes all probe and jig capacitance

Figure 4. Test Circuit

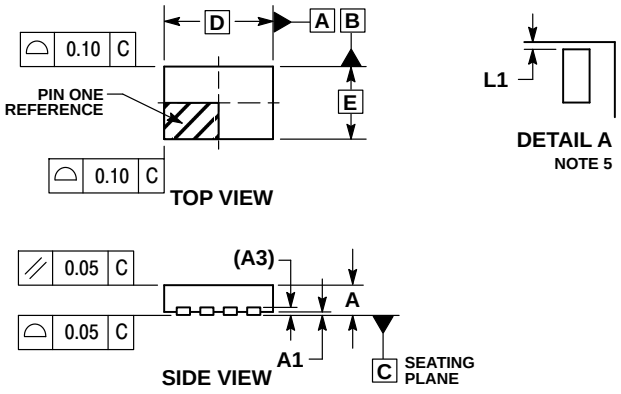
ORDERING INFORMATION

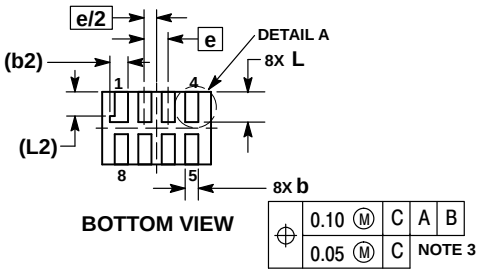
Device	Package	Shipping†
NLU3G16MUTAG	UDFN8 (Pb−Free)	3000 / Tape & Reel
NLU3G16AMX1TCG	ULLGA8, 1.95 x 1.0, 0.5P (Pb−Free)	3000 / Tape & Reel
NLU3G16DMUTCG	UDFN8, 1.95 x 1 (Pb−Free)	3000 / Tape & Reel
NLU3G16EMUTCG	UDFN8, 1.6 x 1 (Pb−Free)	3000 / Tape & Reel
NLU3G16FMUTCG	UDFN8, 1.45 x 1 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

UDFN8 1.8x1.2, 0.4P
CASE 517AJ
ISSUE O

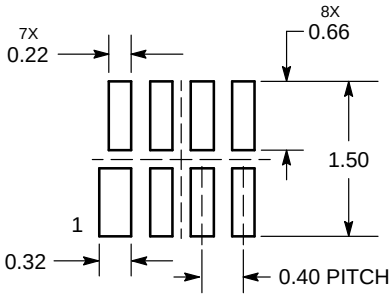




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
4. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH MAY NOT EXCEED 0.03 ONTO BOTTOM SURFACE OF TERMINALS.
5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.127 REF	
b	0.15	0.25
b2	0.30 REF	
D	1.80 BSC	
E	1.20 BSC	
e	0.40 BSC	
L	0.45	0.55
L1	0.00	0.03
L2	0.40 REF	

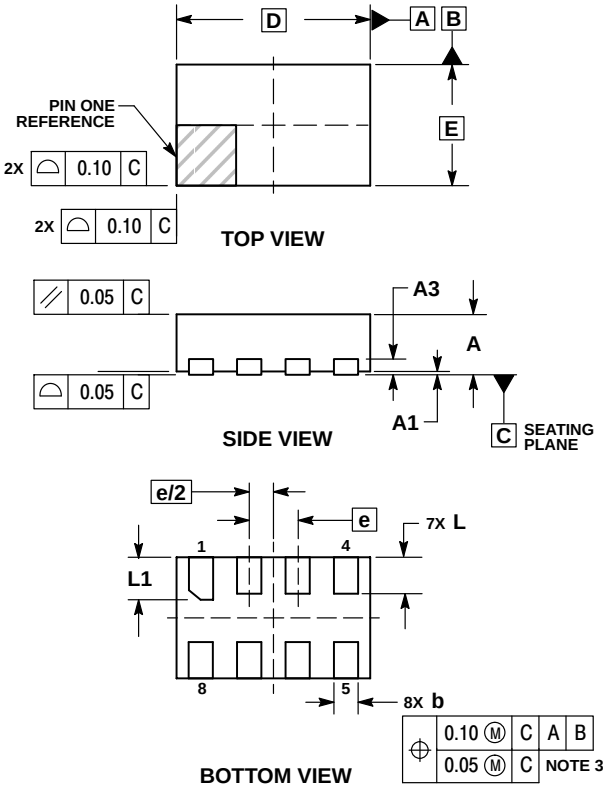
MOUNTING FOOTPRINT
SOLDERMASK DEFINED



DIMENSIONS: MILLIMETERS

PACKAGE DIMENSIONS

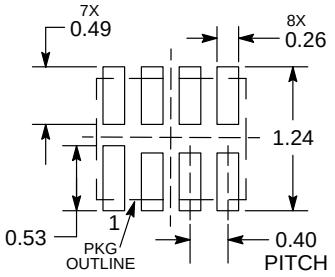
UDFN8, 1.6x1, 0.4P
CASE 517BY
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.60 BSC	
E	1.00 BSC	
e	0.40 BSC	
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*

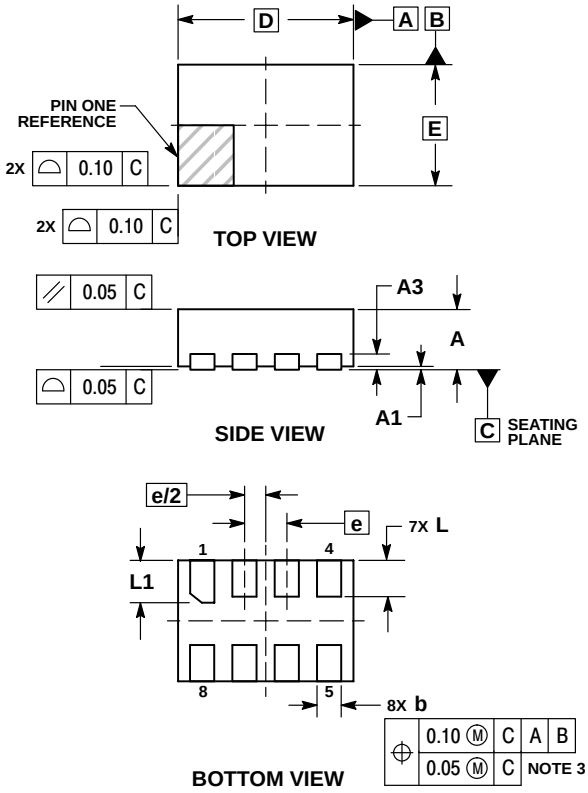


DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

UDFN8, 1.45x1, 0.35P
CASE 517BZ
ISSUE O



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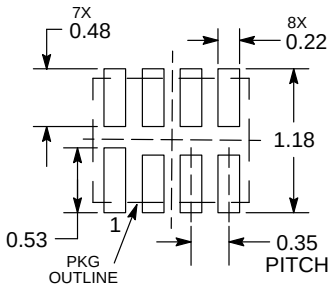
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.45 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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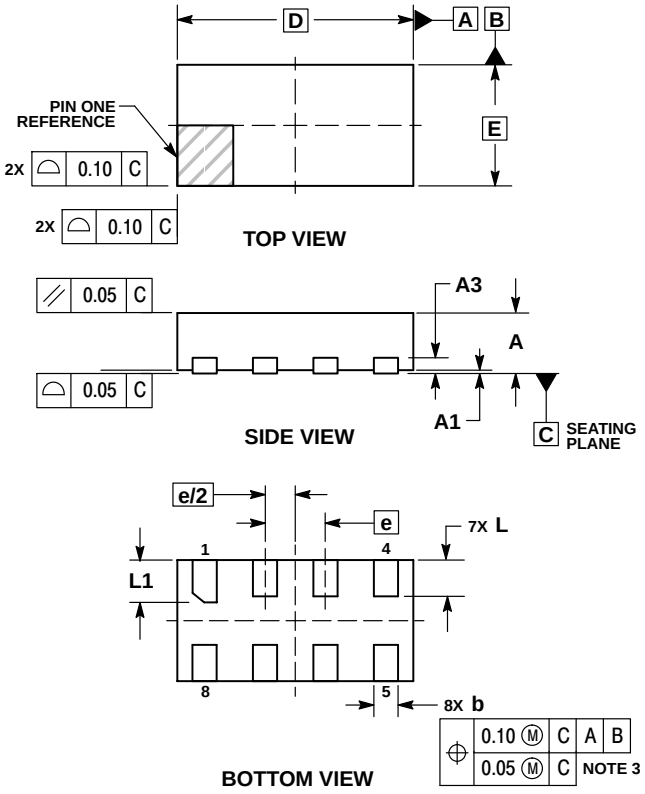
PACKAGE DIMENSIONS

UDFN8, 1.95x1, 0.5P
CASE 517CA
ISSUE O



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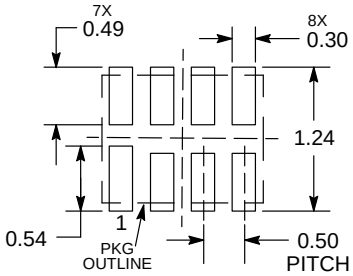
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.95 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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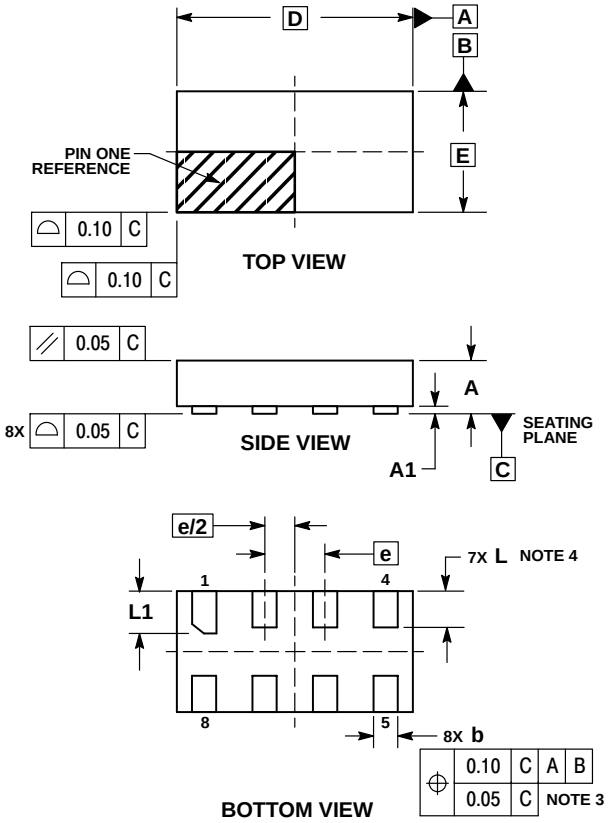
PACKAGE DIMENSIONS

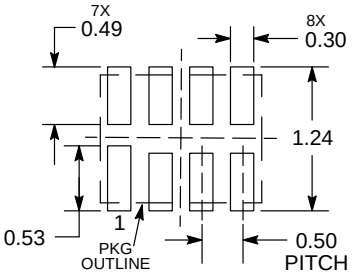
ULLGA8 1.95x1.0, 0.5P
CASE 613AC
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

	MILLIMETERS	
DIM	MIN	MAX
A	−−−	0.40
A1	0.00	0.05
b	0.15	0.25
D	1.95 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.25	0.35
L1	0.30	0.40

MOUNTING FOOTPRINT SOLDERMASK DEFINED*



DIMENSIONS: MILLIMETERS

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PUBLICATION ORDERING INFORMATION

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NLU3G16/D